

INTERNATIONAL STANDARD

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**Field Device Integration (FDI) –
Part 4: FDI Packages**

**Intégration des appareils de terrain (FDI) –
Partie 4: Paquetages FDI**



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Part 4: FDI Packages**

**Intégration des appareils de terrain (FDI) –
Partie 4: Paquetages FDI**

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FIELD DEVICE INTEGRATION (FDI) –**Part 4: FDI Packages****FOREWORD**

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CDV	Report on voting
65E/347/CDV	65E/424/RVC

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A list of all parts in the IEC 62769 series, published under the general title *Field Device Integration (FDI)*, can be found on the IEC website.

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The International Electrotechnical Commission (IEC) draws attention to the fact that it is claimed that compliance with this document may involve the use of patents concerning

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FIELD DEVICE INTEGRATION (FDI) –

Part 4: FDI Packages

1 Scope

This part of IEC 62769 specifies the FDI Packages. The overall FDI architecture is illustrated in Figure 1. The architectural components that are within the scope of this document have been highlighted in this figure.

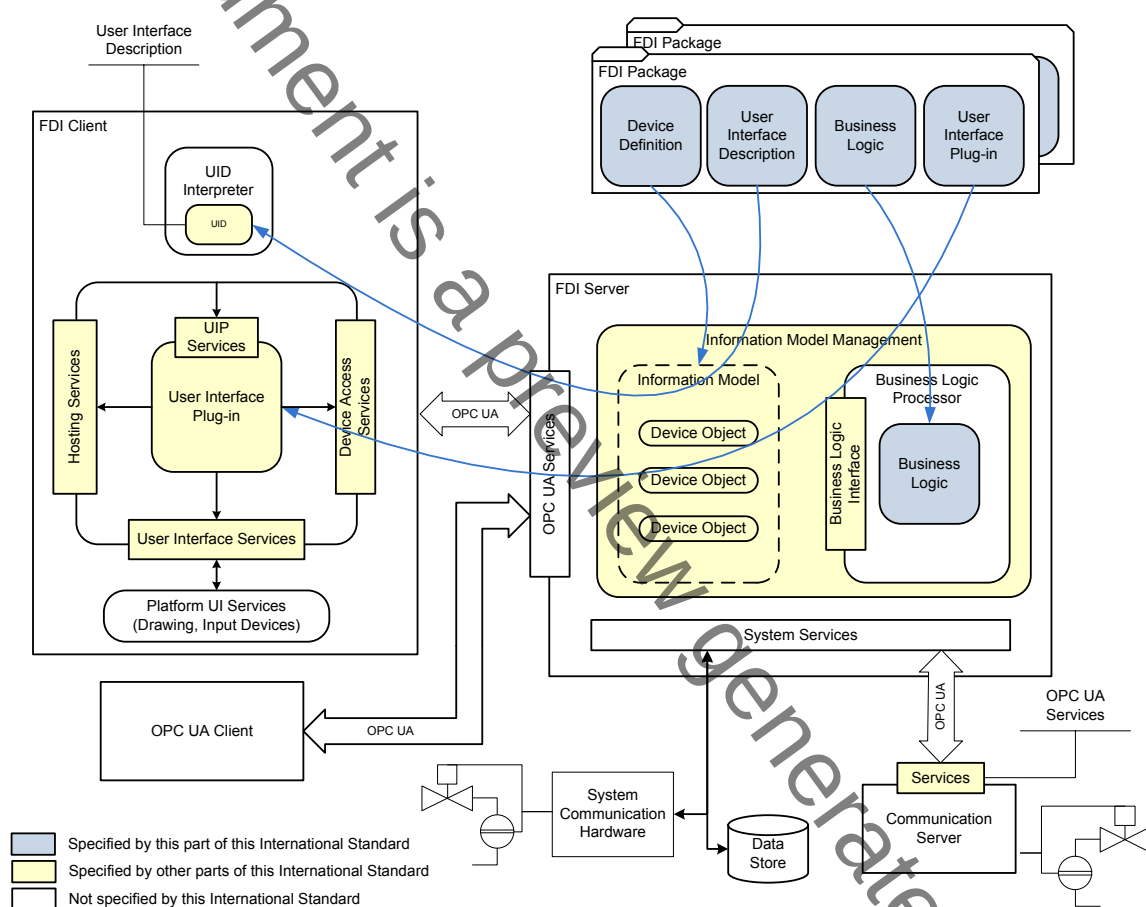


Figure 1 – FDI architecture diagram

2 Normative references

The following documents, in whole or in part, are normatively referenced in this document and are indispensable for its application. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 61804 (all parts), *Function blocks (FB) for process control and Electronic Device Description Language (EDDL)*

IEC 61804-3¹, *Function blocks (FB) for process control and Electronic Device Description Language (EDDL) – Part 3: EDDL syntax and semantics*

IEC 61804-4:–2, *Function blocks (FB) for process control and Electronic device description language (EDDL) – Part 4: EDD interpretation*

IEC 62769-1, *Field Device Integration (FDI) – Part 1: Overview*

NOTE IEC 62769-1 is technically identical to FDI-2021.

IEC 62769-5, *Field Device Integration (FDI) – Part 5: FDI Information Model*

NOTE IEC 62769-5 is technically identical to FDI-2025.

IEC 62769-6, *Field Device Integration (FDI) – Part 6: FDI Technology Mapping*

NOTE IEC 62769-6 is technically identical to FDI-2026.

IEC 62769-7, *Field Device Integration (FDI) – Part 7: FDI Communication Devices*

NOTE IEC 62769-7 is technically identical to FDI-2027.

ISO/IEC 11578, *Information technology – Open Systems Interconnection – Remote Procedure Call (RPC)*

ISO/IEC 29500-2:2011, *Information technology – Document description and processing languages – Office Open XML File Formats – Part 2: Open Packaging Conventions*

ISO 639-1, *Codes for the representation of names of languages – Part 1: Alpha-2 code*

ISO 32000-1, *Document management – Portable document format – Part 1: PDF 1.7*

Extensible Markup Language (XML) 1.0, W3C Recommendation, available at <<http://www.w3.org/TR/REC-xml/>>

XML Schema Definition Language (XSD) 1.1, W3C Recommendation, available at <<http://www.w3.org/TR/xmlschema11-1/>>

3 Terms, definitions, abbreviated terms and acronyms

3.1 Terms and definitions

For the purposes of this document, the terms and definitions given in IEC 62769-1, ISO/IEC 29500-2, and the following apply.

3.1.1

attachment

device and protocol specific support files that are not directly used to integrate the Device into the system

¹ To be published.

² To be published.